

ABSTRACT OF THE DISCLOSURE

Die pads are provided which reduce moisture retention and thermal mismatch by employing a number of die pad sections or a die pad support portion with a number of relief regions. In each case, the die pad area to die area ratio is reduced to improve the thermal 5 mismatch between the die and the die pad. Also, the die pad sections or relief regions are arranged in a spaced apart fashion to provide moisture escape paths between the die and the die pad.